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6	1		USPAT	2003/04/26 06:57
8	1		USPAT	2003/04/26 06:57
9	1		USPAT	2003/04/26 07:00
10	1		USPAT	2003/04/26 07:00
11	1		USPAT	2003/04/26 07:00
12	0	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:20
13	0	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:21
14	48	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:21
15	38	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT	2003/04/26 07:51
16	1	134/\$.ccls. and curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:12
19	158	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:13
22	1	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and clean\$3.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:13
25	1	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (removal clean\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:14
26	130	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:23
29	361	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:24
30	361	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3 skin face pore).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:30
31	0	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3 skin face pore).ti. and pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:31
32	0	curable near1 polymer and pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:31

33	84	pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:44
34	2	pore near2 cleaning and (polyimide lacquer latex rubber near1 cement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:47
35	3684	polyimide and adhesive and cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:47
36	3684	polyimide and adhesive and cleaning sacrificail and coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48
37	244	polyimide and adhesive and cleaning and sacrificial and coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48
38	244	polyimide and adhesive and cleaning and sacrificial and coating and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48
39	20	polyimide and adhesive and cleaning and sacrificial and coating and surface and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:49
40	18	polyimide and adhesive and cleaning and sacrificial and coating and surface and curable and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:49
45	1		USPAT	2003/04/26 09:36
46	1		USPAT	2003/04/26 09:36
47	1		USPAT	2003/04/26 09:36
48	1		USPAT	2003/04/26 09:36
49	1		USPAT	2003/04/26 09:36
50	1		USPAT	2003/04/26 09:36
58	2	"20020189635"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 09:50
59	38370	sonic near5 clean\$3 and dislodge near6 particulate matter and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
60	0	sonic near5 clean\$3 and dislodge near6 particulate near3 matter and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
61	0	sonic near5 clean\$3 and dislodge near6 (particulate matter) and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
62	68	sonic near5 clean\$3 and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03





	252	particle near3 removal and (adhesive adhere adherent) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:24
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	86035	polymer and adhesive and (heat energy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 09:40
	198	polymer and adhesive and (heat energy) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 10:39
	26	polymer and adhesive and (heat energy) and 134/\$.ccls. and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 10:39
	36130	adhesive and curable polymer\$3 and clean\$3 and (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:58
	27984	adhesive and curable polymer\$3 and clean\$3 near22 (wafer semiconductor) and 234/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:59
	0	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor) and 234/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:59
	1	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 13:02
	50	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 13:04